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AMENDMENTS TO THE SPECIFICATION

Please replace paragraph **[0002]** with the following paragraph:

[0002] The following co-pending and commonly-assigned U.S. Patent Applications, filed on even date herewith, are also incorporated herein by reference in their entirety:

1. U.S. Patent Application Serial No. 10/731,869, entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed December 9, 2003, ~~assigned Attorney Docket No.: 1023-318US01/P-10891.00~~;

2. U.S. Patent Application Serial No. 10/731,868, entitled "IMPLANTATION OF LOW-PROFILE IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed December 9, 2003, ~~assigned Attorney Docket No.: 1023-330US01/P-11795.00~~;

3. U.S. Patent Application Serial No. 10/731,699, entitled "COUPLING MODULE OF A MODULAR IMPLANTABLE MEDICAL DEVICE," to Darren A. Janzig et al., and filed December 9, 2003, ~~assigned Attorney Docket No.: 1023-331US01/P-11796.00~~;

4. U.S. Patent Application Serial No. 10/730,873, entitled "OVERMOLD FOR A MODULAR IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed December 9, 2003, ~~assigned Attorney Docket No.: 1023-332US01/P-11798.00~~;

5. U.S. Patent Application Serial No. 10/731,881, entitled "REDUCING RELATIVE INTER-MODULE MOTION IN A ~~DISTRIBUTED~~ MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed December 9, 2003, ~~assigned Attorney Docket No.: 1023-333US01/P-11797.00~~;

6. U.S. Patent Application Serial No. 10/730,877, entitled "LOW-PROFILE IMPLANTABLE MEDICAL DEVICE," to Darren A. Janzig et al., and filed December 9, 2003, ~~assigned Attorney Docket No.: 1023-335US01/P-11801.00; and~~

7. U.S. Patent Application Serial No. 10/731,867, entitled "CONCAVITY OF AN IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed December 9, 2003, ~~assigned Attorney Docket No.: 1023-336US01/P-11800.00.~~; and

8. U.S. Patent Application Serial No. 10/731,638, entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., filed December 9, 2003, ~~assigned Attorney Docket No.: P-20542.00.~~

Please replace paragraph **[0031]** with the following paragraph:

[0031] In the typical embodiment depicted in FIG. 1B, IMD 101 includes three modules, namely, a control module 103, a power supply module 104 and a recharge module 105. Control module 103 typically includes the electronic components associated with the functions of IMD 101. In a typical implementation, control module 103 may include a hybrid circuit that includes digital circuits such as integrated circuit chips and one or more microprocessors, and analog circuit components. Accordingly, control module 103 may also be referred to as an electronic module. The housing of control module 30 may be hermetic in order to protect the control electronics therein, and in some embodiments, may be formed of a rigid material, such as titanium, stainless steel, or a ceramic. Power supply module 104 typically comprises one or more energy storage devices, such as a rechargeable lithium ion battery. In some embodiments, the housing of power supply module 104 may be hermetic, and in some embodiments, may be formed of titanium, stainless steel, or a ceramic. Power source module 104 may include an insulator within its housing to isolate the housing from the power source. Recharge module 105 typically includes one or more coils for transmitting or receiving electromagnetic energy through the scalp. The transmitted energy may include energy to be stored in power supply module 104. In some embodiments, the transmitted energy may also include communication, such as information encoded in radio frequency transmissions. The housing of recharge module 105 need not be hermetic, and may be formed of materials such as silicone, polymers and ceramics.

Please replace paragraph **[0032]** with the following paragraph:

[0032] Individual modules 103 and 104 may be encased in biocompatible metal shields such as titanium shield halves, and may be sealed against contamination. For example, as previously described, control module 103 and/or power supply module 104 may be hermetically sealed to protect against contamination. In addition, individual modules 103 and 104 may include insulation to electrically isolate the electrical components inside the modules from the metal shields. The modules are coupled to an overmold 106 which may be made of a biocompatible material. Use of the term "overmold" herein is not intend to limit the invention to embodiments

in which the overmold is a molded structure. Overmold may be a molded structure, or may be a structure formed by any process.

Please replace paragraph **[0058]** with the following paragraph:

[0058] In both FIGS. 8A and 8B, a lead interconnect device 813 is included within the non-elastomeric components 831 of overmold 822. More particularly, FIGS. 8A and 8B illustrate lead interconnect device 813 embedded within non-elastomeric components 831 of overmold 822. In these examples, the non-elastomeric component 831 restrains control module 810 and external leads 843. Typically, the external leads have iso-diametric proximal ends for connection of the external leads 843 to IMD 801. An external lead 843 is inserted into the lead connection module in order to connect the external leads 843 to electronics within control module 810 of IMD 801. This electrical connection from the control module 810 to the external leads 843 is made using a module connection lead wire 846 that extends from control module 810 and physically connects with the external lead 843 within the lead connection module 813.